



Product / Package Information	
Package	SOIC_W
Body Size	300 mils
Lead Count	20
Terminal Finish	100Sn
MS Number	MS000539B

Environmental Compliance Information	
RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Silica	60676-86-0	3.46 E-01	87.70	877000	60.92	609215	
Thermosets	Phenol Resin	Proprietary	1.58 E-02	4.00	40000	2.78	27786	
Thermosets	Epoxy Resin 1	Proprietary	1.18 E-02	3.00	30000	2.08	20840	
Thermosets	Epoxy Resin 2	Proprietary	1.38 E-02	3.50	35000	2.43	24313	
Others	Others	Proprietary	5.92 E-03	1.50	15000	1.04	10420	
Other inorganic materials	Carbon Black	1333-86-4	1.18 E-03	0.30	3000	0.21	2084	
Subtotal			3.94 E-01	100.0	1000000	69.47	694658	

Leadframe								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Copper & its alloys	Copper	7440-50-8	1.48 E-01	97.5	975000	26.08	260792	
Copper & its alloys	Iron	7439-89-6	3.57 E-03	2.35	23500	0.63	6286	
Copper & its alloys	Zinc	7440-66-6	1.82 E-04	0.12	1200	0.03	321	
Copper & its alloys	Phosphorus	7723-14-0	4.56 E-05	0.03	300	0.01	80	
Subtotal			1.52 E-01	100	1000000	26.75	267479	

Internal Leadframe Plating								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Silver	7440-22-4	1.27 E-03	100	1000000	0.22	2238	

External Leadframe Plating								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Tin & its alloys	Tin	7440-31-5	3.78 E-03	100	1000000	0.67	6659	

Bond Wires								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Gold	7440-57-5	7.89 E-04	100.0	1000000	0.14	1390	

Chip								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Doped Silicon	7440-21-3	1.25 E-02	100	1000000	2.21	22054	

Die Attach								
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Silver	7440-22-4	2.41 E-03	77.00	770000	0.43	4252	
Other organic materials	Acrylic resin	Proprietary	2.19 E-04	7.00	70000	0.04	387	
Other organic materials	Acrylate	Proprietary	1.72 E-04	5.50	55000	0.030	304	
Other organic materials	Polybutadiene derivative	Proprietary	1.41 E-04	4.5	45000	0.025	249	
Other organic materials	Epoxy resin	Proprietary	7.84 E-05	2.5	25000	0.014	138	
Other organic materials	Butadiene Copolymer	Proprietary	4.70 E-05	1.5	15000	0.008	83	
Others	Additive	Proprietary	4.70 E-05	1.5	15000	0.008	83	
Others	Peroxide	Proprietary	1.57 E-05	0.5	5000	0.003	28	
Subtotal			3.14 E-03	100	1000000	0.55	5522	

Package Totals	Weight (g)	Percentage (%)	PPM
	5.68 E-01	100	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



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